

(b) Amendments to the Claims

Kindly cancel claims 1-19 without prejudice or disclaimer of subject matter.

Please add new claims 20-26 as follows. A detailed listing of all the claims is provided.

20. (New) A plating apparatus comprising:

a plating vessel for holding a plating bath containing at least metal ions;

a conveying device for conveying a long conductive substrate and immersing the long conductive substrate in the plating bath;

a facing electrode disposed in the plating bath so as to face one surface of the conductive substrate;

voltage application means for performing plating on the one surface of the conductive substrate by applying a voltage between the conductive substrate and said facing electrode; and

a member fixedly disposed in said plating vessel so that at least a portion of said member contacts a surface of the conductive substrate opposite to the one surface, at least the portion being conductive,

wherein said member comprises a plurality of first members and a plurality of second members in a longitudinal direction of the conductive substrate,

wherein a plurality of said first members are disposed with a gap between adjacent ones of said members and are fixed by supporting members, and wherein each of said second members is dispersed over upper surfaces of two adjacent first members,

wherein a surface of said first member facing a surface of the conductive substrate is substantially flat, wherein said second member includes a projection for filling the gap, and wherein a surface of said projection facing the conductive substrate and a surface of said first member facing the conductive member are disposed on substantially the same plane, and

wherein said second member is detachable from said member.

21. (New) A plating apparatus according to claim 20, wherein said member comprises magnets for maintaining contact with the conductive substrate.

22. (New) A plating apparatus according to claim 20, wherein said member is extended outside of the shorter-direction edge of the conductive substrate.

23. (New) A plating apparatus according to claim 20, wherein said member comprises foot members for supporting at least the conductive portion.

24. (New) A plating apparatus according to claim 20, wherein said member comprises foot members for supporting said first members.

25. (New) A plating method conducted in the plating apparatus of claim 20, including conveying a long conductive substrate while causing it to pass through a plating bath held in a plating vessel and performing electroplating on one surface of the conductive substrate in the plating bath, said method comprising the step of:

suppressing film deposition on a surface of the conductive substrate opposite to the one surface by fixedly disposing a member for film deposition suppression set to substantially the same potential as the conductive substrate in the plating vessel so as to be close to shorter-direction edges of the conductive substrate on the other surface.

26. (New) A plating method according to claim 25, wherein the conductive substrate is conveyed while causing the member for film-deposition suppression means to contact the conductive substrate by a magnetic force.